



09-17-2008



Docket No.: 075905-0057

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To the Director of the U. S. Patent and Trade

Documents or the new address(es) below.

802-1-6

1. Name of Conveying Party(ies)
Motohiro YAMAZAKI, Ryoji INABA, Kosaku TOYOSAKI, Shintaro KUBO, Takashi GOMI, Katsunobu HAMA, Kiyotoshi MORI, and Hideyuki AKIYAMA

Additional name(s) of conveying party(ies) attached? Yes No

3. Nature of Conveyance/Execution Date(s)

Execution Date(s): August 29, 2008, July 24, 2008, July 25, 2008, July 24, 2008, July 24, 2008, August 1, 2008, July 25, 2008, July 28, 2008 (respectively)

- Assignment, Security Agreement, Joint Research Agreement, Government Interest Assignment, Executive Order 9424, Confirmatory License, Other, Merger, Change of Name

2. Name and address of receiving party(ies)
Name: HITACH HIGH-TECHNOLOGIES CORPORATION

Internal Address:

Address: 1-24-14, Nishi Shinbashi, Minato-Ku Tokyo, JAPAN

Additional name(s) & address(es) attached? Yes No

4. Application or patent number(s):

A. Patent Application No(s). 12/146,920

This document is being filed together with a new application.

B. Patent No(s).

Additional numbers attached? Yes No

5. Name and address to whom correspondence concerning document should be mailed:

Name: MCDERMOTT WILL & EMERY LLP
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6. Total number of applications and patents involved:

7. Total fee (37 CFR 1.21(h) & 3.41) \$40.00
 Authorized to be charged by credit card
 Authorized to be charged to deposit account
 Enclosed
 None required (government interest not affecting title)

8. Payment Information:

a. Credit Card Last 4 Numbers _____ Expiration Date _____
b. Deposit Account Number 500417
Authorized by Name 00000094 500417 12146920

9. Signature.

Keith E. George 34,111

Signature: Keith E. George

Date: September 12, 2008

Name and Registration No. of Person Signing

Signature

Date

Total number of pages including cover sheet, attachments and documents: 2

ASSIGNMENT
(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Hitachi High-Technologies Corporation, a corporation organized under the laws of Japan, located at 1-24-14, Nishi Shinbashi, Minato-ku, Tokyo, Japan receipt of which is hereby acknowledged I do hereby sell and assign to said Hitachi High-Technologies Corporation, its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

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invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Hitachi High-Technologies Corporation, its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi High-Technologies Corporation,

Signed on the date(s) indicated aside our signatures:

INVENTOR(S)

(発明者フルネームサイン)

Date Signed

(署名日)

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